



SanDisk® SSD X100

Product Manual

(Released)

Rev 1.0

April 2012

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Document No. 80-11-01842

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Document No. 80-11-01842

04/2012

Printed in U.S.A.

Revision History

Revision	Description	Date
0.2	<ul style="list-style-type: none"> Initial version 	Sep 15, 2011
0.3	<ul style="list-style-type: none"> Updated mSATA drawing Updated 64GB data Add 32GB mSATA configuration 	Oct 25, 2011
0.4	<ul style="list-style-type: none"> Updated performance Added 2.5" 9.5mm configuration Updated word 106: 0x4000 	Nov 15, 2011
0.41	<ul style="list-style-type: none"> Updated mSATA drawing 	Dec 1, 2011
0.5	<ul style="list-style-type: none"> Updated performance (2.3) Updated operating power consumption (3.4) Updated mSATA dimensions (tolerance) (4.3) Added mSATA drawing for keep out areas (4.3) Updated ESD test voltage (5.6) Updated chemical restrictions (5.9) Updated regulations (5.10) Added MTTF data (6.2) Updated Commands set (8.1) Updated Identify Data (8.2) Updated Log Pages (8.3) Updated Ordering information (9) 	Dec 22, 2011
0.6	<ul style="list-style-type: none"> Updated performance (2.3) Updated power consumption (3.3 & 3.4) Updated operating power consumption (3.4) Updated mSATA form factor drawing (4.3) Updated mSATA thickness (4.3) Updated vibration (5.3) Updated shock (5.4) Updated MTTF of 512GB (6.2) Updated Identify Data (8.2) Removed Device Statistics (04h) from Log Pages (8.3) 	Feb 29, 2012
0.7	<ul style="list-style-type: none"> Updated performance (2.3) 	Apr 4, 2012
1.0	<ul style="list-style-type: none"> Updated performance (2.3) Average power consumption (3.3) Updated Identify Data (8.2), word 76 (HIPM enable) 	Apr 19, 2012

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1. Introduction

1.1 General Description

SanDisk SSD X100 is designed to improve the mobile computing user experience with leading performance, high reliability and power efficiency in SATA standard 2.5" and mSATA small form factor.

SanDisk X100 with 32, 64, 128, 256 and 512 gigabyte¹ (GB) flash memory, support performance optimizations such as "Multi Stream" support, performance throttling, and move/copy mega-files in high performance.

With a state of the art and an evolutionary controller design, SanDisk SSD provides more than fast sequential read/write performance and provides significant improved random I/O performance and multi stream capabilities enabling SanDisk SSD to work much faster.

SanDisk, the industry leader in flash storage, is uniquely positioned to drive the paradigm shift in mobile computing to SSDs Inside enterprise and consumers computers, such as the thin & light laptops and transportable laptops.

This manual describes the functional, mechanical and interface specifications for the following SanDisk SSD X100 model drives: SATA 2.5" 7.0mm, SATA 2.5" 9.5mm and SATA mSATA.

¹ 1 megabyte (MB) = 1 million bytes; 1 gigabyte (GB) = 1 billion bytes. Some of the listed capacity is used for formatting and other functions, and thus is not available for data storage.

1.2 Key Features

- Flash Memory used:
 - SanDisk 24nm 64Gb MLC ABL
- Unformatted capacities²:
 - SATA 2.5": 64GB, 128GB, 256GB, 512GB
 - mSATA: 32GB, 64GB, 128GB, 256GB
- Form factors:
 - SATA 2.5" 7.0mm case, complies with SFF-8223 and SFF-8201
 - SATA 2.5" 9.5mm case, complies with SFF-8223 and SFF-8201
 - Standard mSATA form factor with a Mini PCIe edge connector, complies to JEDEC MO-300B standard
- Interface to host:
 - SATA 6Gb/s (Revision 3.0) compliant
 - Backwards compliant to SATA 3Gb/s & SATA 1.5Gb/s
 - ATA 8 Command Set ACS-2
 - NCQ support up to queue depth = 32
 - SMART support
- High performance³:

▪ Maximum Host transfer rate:	6Gb/s
▪ Sustained Sequential Read:	500 MB/s
▪ Sustained Sequential Write:	430 MB/s
▪ 4K Random Write:	43,000 IOPS
▪ 4K Random Read:	76,000 IOPS
▪ Write Latency:	65µs
▪ Read Latency:	55µs
- Low power consumption:

▪ Typical read/write ⁴ :	120mW to 150mW
▪ Slumber power mode ⁵ :	70mW to 100mW

² The logical capacity of the drive conforms to the IDEMA HDD Specification. See www.idema.org for details. Some of the listed capacity is used for formatting and other functions, and thus is not available for data storage. 1 megabyte (MB) = 1 million bytes; 1 gigabyte (GB) = 1 billion bytes.

³ Performance for 256GB product on SATA 6Gb/s host, Queue Depth = 32. Based on internal testing; performance may vary.

⁴ Average (typical) power while running MobileMark™ 2007. X100 is configured with Device Initiated Power Management (DIPM) enabled and Host Initiated Power Management (HIPM) enabled. 120mW for form factors with input power of 3.3V ; 150mW for 2.5" standard SATA (5V).

⁵ With DIPM enabled. 70mW-75mW for form factors with input power of 3.3V ; 100mW for 2.5" standard SATA (5V).

- Advanced Flash Management:
 - nCache™ – Non Volatile Write Cache
 - Support for TRIM
 - Dynamic & Static Wear-leveling
 - Bad Block Management
 - Background Garbage Collection
- Support for Dynamic Performance Throttling:
 - Performance will be throttled in the event junction temperature of critical components is measured to be exceeding the maximum allowable for the product.
- Highly-reliable:
 - At least 5 years useful life
 - Mean time to failure (MTTF): Up to 2,000,000 hrs
 - Uncorrectable Bit Error Rate (UBER): 1 sector per 10^{16} bits read
 - Operating and non-operating shock: 1,500G, 0.5ms half sine
 - Operating vibration: 5gRMS, 10-2000 Hz
 - Non-operating vibration: 4.9gRMS, 2.5-800 Hz
 - Operating temperature: 0°C to 70°C
 - Non-operating temperature and storage⁶: -55°C to +85°C

⁶ Temperature measured on board via temperature sensor, Storage temperature does not guarantee data retention.

1.3 Functional Description

The SSD X100 contains a high-level, intelligent storage subsystem with powerful capabilities.

These capabilities include the following:

- Supports multi stream – improves user experience in multitasking systems
- Support for Trim command
- Minimal write amplification – increases endurance and performance
- Tiered caching – Volatile and non-volatile cache
- Supports ATA register and command set (ATA-8 / ACS2 standard)
- S.M.A.R.T. feature supported
- Host independence from details of erasing and programming flash memory
- Sophisticated system for error recovery including a powerful error correction code (ECC)
- Sophisticated system for managing defects
- Advanced power management for low power operation
- Implementation of dynamic and static wear-leveling to extend SSD X100 life

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1.4 Advanced Flash Management

1.4.1 Defect and Error Management

SSD X100 contains a sophisticated defect and error management system that is similar to the systems found in magnetic disk drives, and in many cases, offers enhancements. If necessary, the SSD device will rewrite data from a defective block to a good block. This action is completely transparent to the host and does not consume any user data space.

The SSD soft error rate specification is much better than the magnetic disk drive specification. In the extremely rare case that a read error does occur, the SSD X100 products have innovative algorithms to recover the data by using error detection code and error correction code (EDC/ECC). These defect and error management systems, coupled with the solid state construction, give SSD X100 unparalleled reliability.

1.4.2 Wear Leveling

Wear leveling is an intrinsic part of the erase pooling functionality of SSDs using NAND memory. Advanced features of dynamic and static wear-leveling, and automatic block management are used to ensure an even distribution of write/erase cycles throughout the entire device, regardless of how dynamic or static the data written is. This guarantees high data reliability and maximizes flash life expectancy.

1.4.3 Bad Block Management

Bad blocks are occasionally created during the life cycle of a flash component, in a phenomenon called dynamic bad-block accumulation. These bad blocks must be marked and replaced dynamically in order to prevent read/write failures. When a bad block is detected, the embedded Bad Block Mapping algorithm maps out the block, which will remove the block from future use.

1.4.4 Tiered Caching

The SSD X100 supports a unique feature to improve random write performance and ensure very positive user experience. Studies show that modern operating systems mostly access the storage device using small access blocks, with the majority being 4KB access blocks.

The small logical access blocks conflict with the physical block structure (>1MB) for the newer generation flash memory technology. Therefore, to bridge this difference, SSD X100 employs three storage layers:

- Volatile cache - DDR DRAM cache
- nCache™ - A non-volatile flash write cache
- Mass storage – MLC NAND flash

The nCache™ is used to accumulate small writes (called segments) at high speed and then flush & consolidate them to larger MLC section of the NAND Flash memory array.

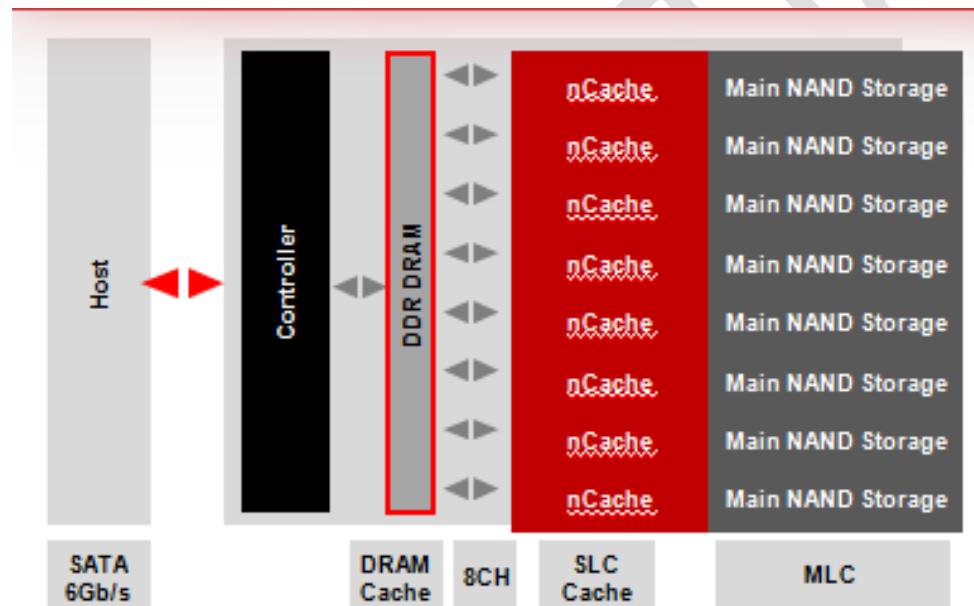


Figure 1-1: SanDisk SSD X100 Tiered Caching Technology

1.5 Advanced Power Management

SSD X100 supports an advanced power management system that includes both Host Initiated Power Management (HIPM) and Device Initiated Power Management (DIPM).

1.5.1 Slumber SATA low power mode

The SanDisk SSD x100 supports entering into Slumber SATA low power mode through DIPM (Device Initiated Power Management) as well as HIPM (Host Initiated Power Management). Upon completion of any command, in case of DIPM, the SSD will request the host to enter into Slumber power.

1.6 Background Garbage Collection

Once the SSD X100 detects idle time, the flash management firmware can utilize the time the device is idle in order to perform internal house-keeping operations. These internal house-keeping activities include freeing up the space in the nCache by flushing and consolidating to the MLC storage and rearranging the data in MLC array. Performing internal house-keeping activities in background will significantly improve performance of the device, providing swift user experience. These operations are executed internally and are transparent to the host. Any time a new command is received from the host the internal operations will be terminated and the host command will be serviced with minimal delay.

1.7 Performance Throttling

In order to protect the integrity of the data and prevent excessive heat dissipation, the SSD X100 utilizes an on-board/on-chip thermal sensor to monitor the SSD's critical component junction temperature. If the temperature rises above the allowable limit, the performance will be reduced until the temperature decreases to an allowable level. This performance throttling technique acts as a safety measure.

2. General Product Specifications

2.1 Interface

The SSD X100 interface complies with the Serial ATA standard published by ANSI. The device complies with the SATA 6Gb/s, Revision 3.0 specifications and supports ATA-8 Command Set ACS-2.

For more information, refer to the American National Standard X3.221: AT Attachment for Interface for Disk Drives document. Documentation can be ordered from IHS by calling 1-800-854-7179 or accessing their Web site: <http://global.ihs.com>

2.2 Capacity

Unformatted Capacity ⁷	Total Number of User-Addressable Sectors in LBA Mode ⁸	Number of Logical Cylinders	Number of Logical Heads	Number of Logical Sectors per Track
32GB	62,533,296	16,383	16	63
64GB	125,045,424	16,383	16	63
128GB	250,069,680	16,383	16	63
256GB	500,118,192	16,383	16	63
512GB	1,000,215,216	16,383	16	63

Table 2-1: SanDisk SSD X100 Capacity Specification

⁷ 1 gigabyte (GB) = 1 billion bytes. Some of the listed capacity is used for formatting and other functions, and thus is not available for data storage.

⁸ 1 Sector = 512 bytes.

2.3 Performance⁹

Parameter	Unit	NCQ	32GB	64GB	128GB	256GB	512GB
SATA 6Gb/s host interface							
Sequential Read	MB/s	QD=32	295	495 ¹⁰	500	500	480
Sequential Write	MB/s	QD=32	95	190	355	430	410
Random Read [4KB]	IOPs	QD=1	6,850	7,450	7,450	7,450	7,250
		QD=32	45,500	70,000 ¹¹	74,000	76,000	75,000
Random Write [4KB]	IOPs	QD=1	19,500	21,000	21,000	21,000	21,000
		QD=32	21,500	34,000	38,000	43,000	42,500
Read/Write Latency ¹²	us	-	55/65	55/65	55/65	55/65	55/65
Typical power-on ready time ¹³	Sec	-	0.3	0.75 ¹⁴	0.8	0.9	1

Table 2-2: SanDisk SSD X100 Performance

2.4 Endurance

Parameter	32GB	64GB	128GB	256GB	512GB
Long Term Data Endurance (LDE) ¹⁵	>40TBW	>80TBW	>80TBW	>80TBW	>80TBW

Table 2-3: SanDisk SSD X100 Endurance

⁹ Measured using IOMETER 2006.07.27 on Intel® Core™ i7-2600 Processor based Windows7™PC, secondary drive configuration with host write cache enabled. Measurements are performed on 8GB of LBA range.

¹⁰ 64GB: Sequential read 495MB/s for mSATA FF, 410MB/s for 2.5" FF

¹¹ 64GB: Random read 70,000 IOPs for mSATA FF, 67,000 IOPs for 2.5" FF

¹² Measured in sequential 4KB with QD=1

¹³ Power on to Ready Time assumes Graceful Shutdown

¹⁴ 64GB: Typical power-on ready time is 0.75 sec for mSATA FF and 0.3 sec for 2.5" FF

¹⁵ LDE is calculated based on typical workload based on Windows OS. LDE is a direct function of user workload and access pattern. LDE is defined in terms of Terabytes Written, "TBW."

3. Power Characteristics

3.1 Supply Voltage

Parameter		Specifications
Input Voltage	Form Factor	
	Standard SATA connector	5V ± 5%
	mSATA	3.3V ± 5%
Maximum Ripple		100mV (peak to peak), 0 – 30MHz
Supply Rise Time		100msec

Table 3-1: SanDisk SSD X100 Supply Voltage

3.2 Graceful Power-off Requirements

By default, most Operating Systems operate with Host Write Cache ‘enabled,’ which more accurately means there can be data residing in the X100 that hasn’t been successfully programmed into flash memory (this is a feature of ATA and not specific to SanDisk SSD products). To ensure this data is properly committed to flash memory, the X100 requires a Flush Cache command followed by a Standby Immediate command prior to power being removed. This command sequence allows the X100 to complete the programming of all data in its volatile data cache into flash memory, returning ‘good’ status to the host only after successful completion. This command sequence is handled transparently by most OS’s during a standard shutdown sequence (e.g., hibernation, shutdown, standby, etc).

However, it is possible that in some applications (e.g., embedded systems without a typical user-interface providing graceful power-down options), power to the X100 could be removed, without warning, precluding the possibility of a graceful shutdown – resulting in the possibility of data loss and/or longer power on time.

3.3 Average Power Consumption¹⁶

Average power consumption is defined as the blended read/write/idle power used by the SSD X100 while it is operating with a typical OS installed. The power consumption is being measured while running MobileMark™ 2007 with Device Initiated Power Management (DIPM) enabled (allowing the SSD X100 to enter low power modes during host idle time). MobileMark™ 2007 simulates the usage of standard user applications in the Windows environment, providing a reproducible test platform for measuring average power consumption.

Input Voltage	Parameter	32GB	64GB	128GB	256GB	512GB
SATA 6Gb/s host interface						
5V ± 5%	Read/Write [mW]	NA	150	150	150	150
3.3V ± 5%	Read/Write [mW]	120	120	120	120	NA

Table 3-2: SanDisk SSD X100 Average Power Consumption

¹⁶ Power measurements in 25 °C. Based on FW version with HIPM-enable.

3.4 Operating Power Consumption – Average Max

Operating power consumption is measured while the X100 is continuously processing sequential read and write commands (tested separately) with a transfer size of 256 sectors per command (128KB). Sampling interval is 1 second. Measurement of operating power consumption is meant to demonstrate the worst-case continuous power required by the SSD X100 during long read or write command sequences.

Input Voltage	Parameter	32GB	64GB	128GB	256GB	512GB
SATA 6Gb/s host interface						
5V ± 5%	Read [mW]	NA	2,250	2,700	2,700	2,700
	Write [mW]	NA	2,300	3,700	4,450	4,450
3.3V ± 5%	Read [mW]	1,650	2,450	2,650	2,650	NA
	Write [mW]	1,450	2,050	3,400	4,200	NA

Table 3-3: SanDisk SSD X100 Active Power Consumption

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3.5 Low Power Mode Consumption

Low power mode consumption is defined as the mode where the SSD X100 has entered Slumber mode (SATA PHY state) and DPDM (SSD X100 specific ‘deep power down mode’ that is entered after a period of IDLE where no ATA commands are received from the host).

Input Voltage	Parameter	32GB	64GB	128GB	256GB	512GB
SATA 6Gb/s host interface						
5V ± 5%	Slumber Mode [mW]	NA	95	100	100	TBD
3.3V ± 5%	Slumber Mode [mW]	70	75	75	75	NA

Table 3-4: SanDisk SSD X100 Power Consumption in Low Power Mode

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4. Physical Specification

4.1 SATA 2.5" 7.0mm form factor

Complies with SFF-8201 & SFF-8223

Parameter	Specifications
Width	69.85mm
Length	100.5mm
Thickness (max)	7.0mm
Typical Weight	66.5±1gr (64,128GB) 69.5±1gr (256,512GB)

Table 4-1: Mechanical Information – 2.5" 7.0mm Form Factor

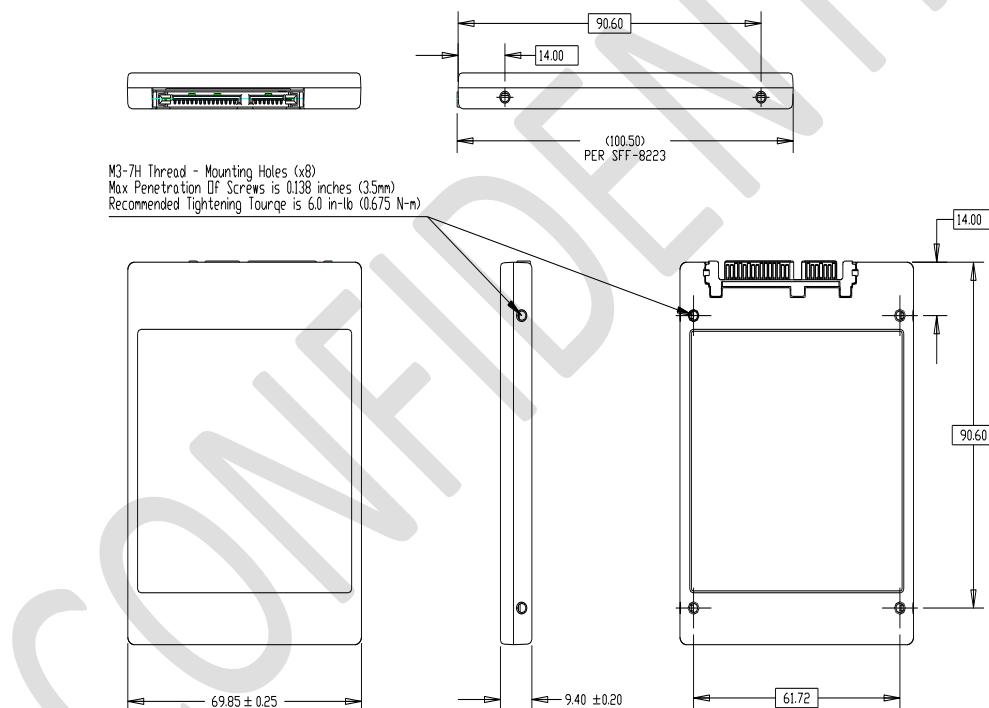


Figure 4-1 : Drawing - 2.5" 7.0mm Form Factor

4.2 SATA 2.5" 9.5mm form factor

Complies with SFF-8201 & SFF-8223

Parameter	Specifications
Width	69.85mm
Length	100.5mm
Thickness (max)	9.5mm
Typical Weight	77±1gr (64,128GB) 81±1gr (256,512GB)

Table 4-2: Mechanical Information – 2.5" 9.5mm Form Factor

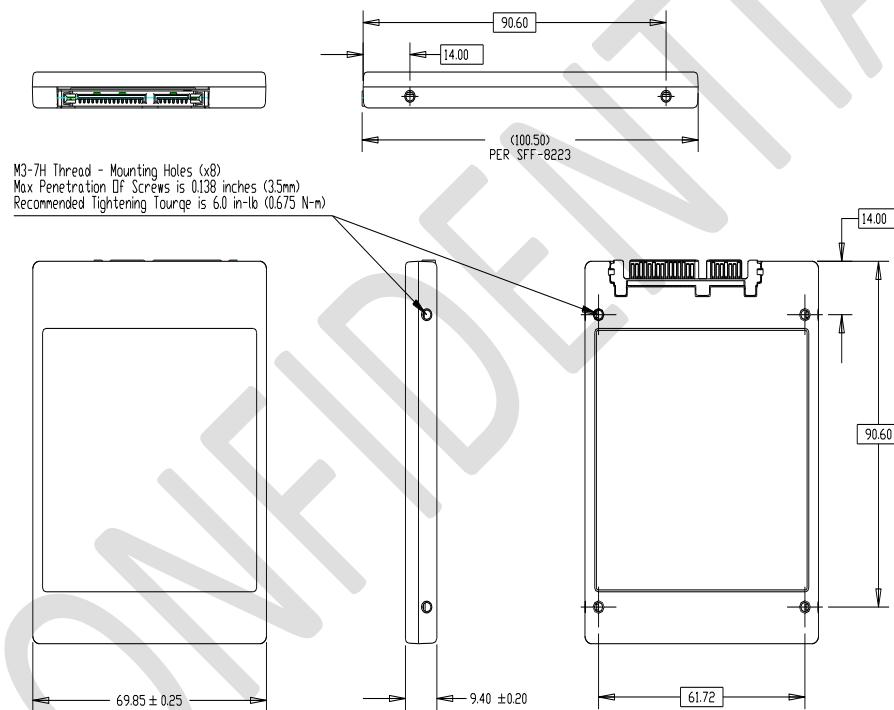


Figure 4-2 : Drawing - 2.5" 9.5mm Form Factor

4.3 mSATA Form Factor

Complies with MO-300B Standard

Parameter	Specifications
Width	29.85±0.15mm
Length	50.80±0.15mm
Thickness (max)	3.6mm
Typical Weight	6.5±0.5gr (32,64GB) 7.5±0.5gr (128,256GB)

Table 4-3: Mechanical Information - mSATA form factor

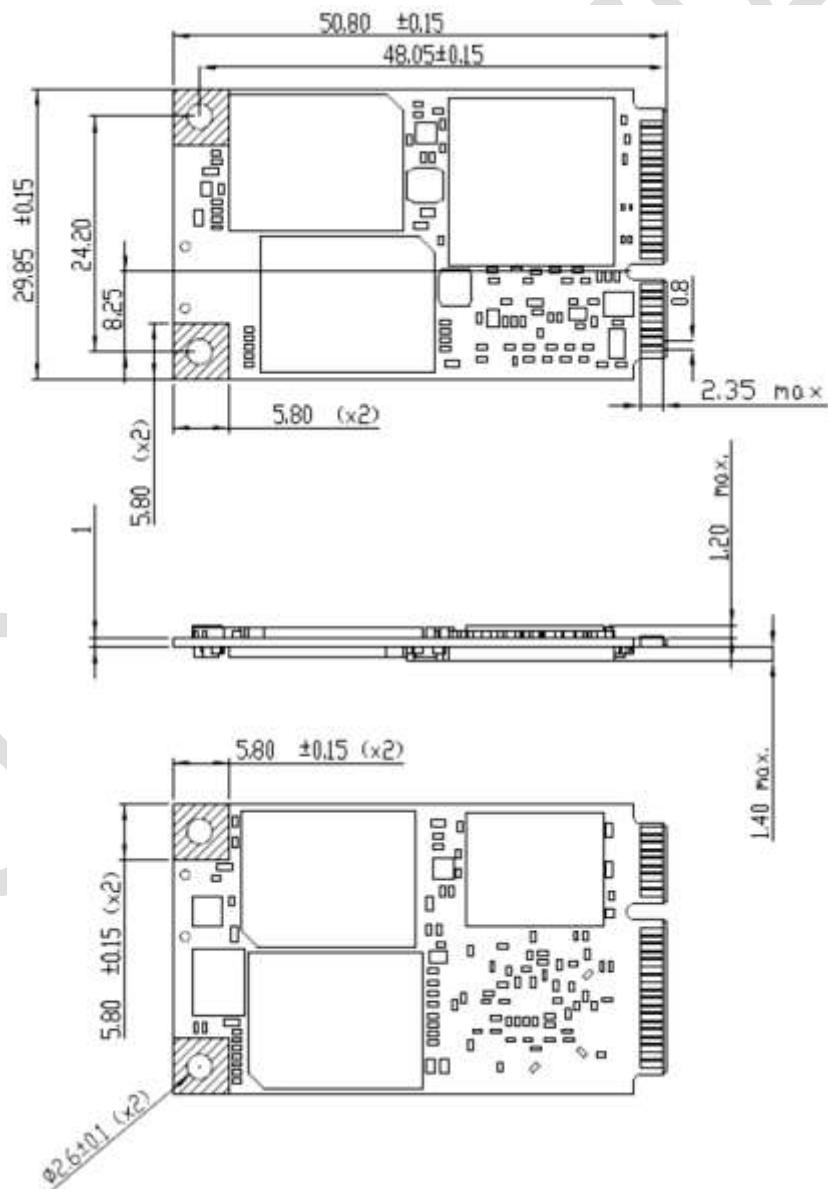


Figure 4-3: Drawing - mSATA Form Factor

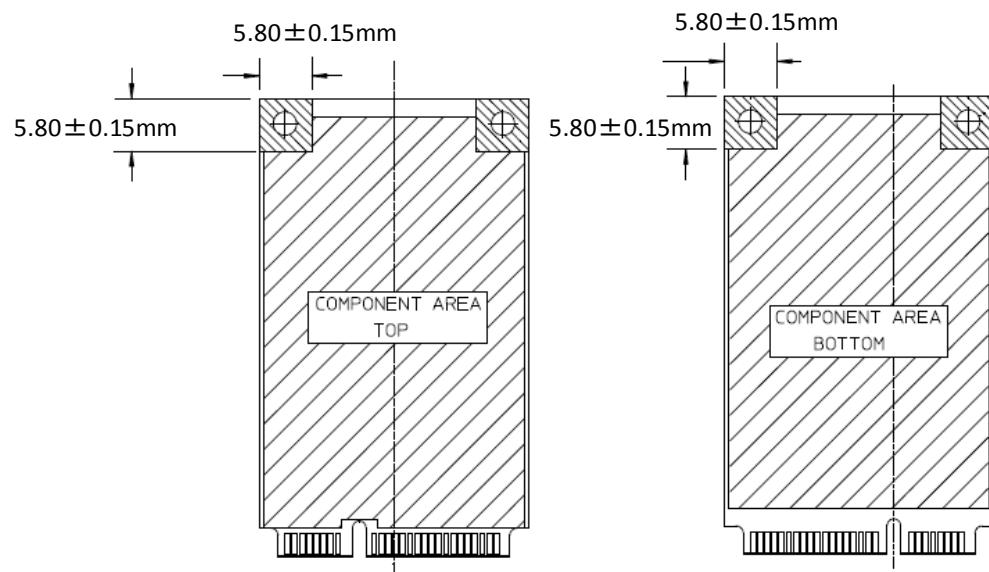


Figure 4-4: Drawing - mSATA Keep Out Area

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5. Environmental Specifications

5.1 Temperature

Parameter	Specifications
Operational ¹⁷	0°C to 70°C
Storage ¹⁸	-55°C to 85°C

Table 5-1: SanDisk SSD X100 Temperature Specification

5.2 Humidity

Parameter	Specifications
Operational	
Humidity (Non condensation)	5% to 95%
Maximum wet bulb	30°C
Non-operational	
Humidity (Non condensation)	5% to 95%
Maximum wet bulb	40°C

Table 5-2: SanDisk SSD X100 Humidity Specification

5.3 Vibration

Parameter	Specifications
Non-operational	4.9gRMS, 2.5-800 Hz, 3 axes
Operational	5gRMS, 10-2000 Hz, 3 axes

Table 5-3: SanDisk SSD X100 Vibration Specification

5.4 Shock

Parameter	Acceleration Force	Half Sine pulse duration
Operational / Non operational	1500G	0.5ms

Table 5-4: SanDisk SSD X100 Shock Specification

¹⁷ Temperature for thermal operational is measured on board with X100 temperature sensor

¹⁸ Storage temperature does not guarantee data retention

5.5 Altitude

Parameter	Specifications
Operational / Non-Operational	-1500ft (-457m) to 40,000ft (12,192m)

Table 5-5: SanDisk SSD X100 Altitude Specification

5.6 Electrostatic Discharge (ESD)

The SanDisk SSD X100 is ESD tested per IEC 61000-4-2 Standard.

Parameter	Test Voltage
Contact	4kV
Air	8kV

Table 5-6: SanDisk SSD X100 ESD Specification

5.7 Acoustics

The SSD X100 does not generate any acoustics noise (0dB).

5.8 EMI/RFI Compliance

The SanDisk SSD X100 is certified to comply with the following standards.

Standard
FCC Part 15 Class B
IECS-003 Class B
EN 55022 Class B
EN 55024
KCC No. 2008-39
KCC No. 2008-38
CNS 13438
VCCI: 2006
AS/NZS CISPR 22: 2006

Table 5-7: SanDisk SSD X100 EMI/RFI Compliance

5.9 Chemical Restrictions

SSD X100 complies with the European Union's Restriction on Use of Hazardous Substances in Electrical and Electronic Equipment (EU RoHS) Directive 2002/95/EC and its amendments European Union's Registration, Evaluation, Authorization and Restriction of Chemicals (REACH), Regulation (EC) 1907/2006.

SSD X100 complies with China's management methods for controlling pollution by electronic information products (China RoHS).

5.10 Regulations

The SanDisk SSD X100 is certified with the following certifications:

Certification/Compliance	Description
UL certificated	UL 60950 US (UL) and UL Canadian (ULc)
CB certificated	EN 60950-1
Technischer Überwachungsverein (TÜV)	EN 60950-1
CE compliant	Conformity with essential health and safety requirements set in European directives of low voltage and EMC
Korea Communication Commission (KCC)	Conformity with Korean ministerial Ordinance
BSMI (Taiwan)	
VCCI (Japan)	Compliance with Voluntary Control Council for Interference by Information Technology Equipment (VCCI)
C-Tick (Australia)	Compliance with EMC framework requirements of Australian Communications Authority (ACA)
FCC	Compliance with FCC 47CFR part 15 subpart B class B
EU RoHS Directive [EU Directive 2002/95/EC]	
EU Packaging Directive [EU Directive 94/62/EC]	
EU WEEE Directive [EU Directive 2002/96/EC]	
EU REACH Regulation	
PFOS Directive [EU Directive 2006/122/EC]	
EU Directive 76/769/EEC	
China RoHS	EPuP (20)

Table 5-8: SanDisk SSD X100 Regulation Standards

6. Reliability Characteristics

6.1 Error Rate

Non-recoverable error rate is 1 error per 10^{16} bits read.

6.2 MTTF (Mean-Time-To-Failure)

The reliability figure of merit most often used for electronic equipment is Mean-Time-To-Failure (MTTF). SanDisk estimates MTTF using a prediction methodology based in accordance with the Telcordia Special Report SR-332. The prediction is based on a Parts Stress Analysis.

Quality levels were defined as industrial grade (I) for all of the components. The detailed prediction for the system was performed at a temperature of 25°C in a GB environment.

The following table summarizes the estimated MTTF results for each capacity.

Capacity	Condition	MTTF (Hours)
32GB	Telcordia SR-332, GB, 25°C	2,000,000
64GB	Telcordia SR-332, GB, 25°C	2,000,000
128GB	Telcordia SR-332, GB, 25°C	2,000,000
256GB	Telcordia SR-332, GB, 25°C	2,000,000
512GB	Telcordia SR-332, GB, 25°C	2,000,000

Table 6-1: SanDisk SSD X100 MTTF

7. Interface

7.1 Supported Standards

The SSD X100 complies with the following standards:

- SATA 6Gb/s, Revision 3.0
- ATA-8 Command Set ACS-2

7.2 Pin Assignments - Standard SATA

SIGNAL Connector Pinout:

Pin #	Signal Name	Description
S1	GND	2nd mate
S2	A+	RxP
S3	A-	RxM
S4	GND	2nd mate
S5	B-	TxM
S6	B+	TxP
S7	GND	2nd mate

POWER Connector Pinout:

Pin #	Signal Name	Description
P1	V33	Not connected
P2	V33	Not connected
P3	V33	Not connected
P4	GND	1st mate
P5	GND	2nd mate
P6	GND	2nd mate
P7	V5	5V power input, pre-charge, 2nd mate
P8	V5	5V power input
P9	V5	5V power input
P10	GND	2nd mate
P11	DAS	Device Activity Signal
P12	GND	1st mate
P13	V12	Not connected
P14	V12	Not connected
P15	V12	Not connected

Table 7-1: Standard SATA Connector Pin Assignment

7.3 Pin Assignments - mSATA

Pin #	Assignment	Description	Pin #	Assignment	Description
1		No Connect	2	+3.3V	3.3V Source
3		No Connect	4	GND	Return Current Path
5		No Connect	6		No Connect
7		No Connect	8		No Connect
9	GND	Return Current Path	10		No Connect
11		No Connect	12		No Connect
13		No Connect	14		No Connect
15	GND	Return Current Path	16		No Connect
17		No Connect	18	GND	Return Current Path
19		No Connect	20		No Connect
21	GND	Return Current Path	22		No Connect
23	+B - TXP	Transmitter Differential Signal Pair	24	+3.3V	3.3V Source
25	-B - TXN	Transmitter Differential Signal Pair	26	GND	Return Current Path
27	GND	Return Current Path	28		No Connect
29	GND	Return Current Path	30		No Connect
31	-A - RXN	Receiver Differential Signal Pair	32		No Connect
33	+A - RXP	Receiver Differential Signal Pair	34	GND	Return Current Path
35	GND	Return Current Path	36		No Connect
37	GND	Return Current Path	38		No Connect
39	+3.3V	3.3V Source	40	GND	Return Current Path
41	+3.3V	3.3V Source	42		No Connect
43		No Connect	44		No Connect
45		No Connect	46		No Connect
47		No Connect	48		No Connect
49	DA/DSS	Device Activity	50	GND	Return Current Path
51	Presence Detection	Pulled low by device	52	+3.3V	3.3V Source

Table 7-2: mSATA Connector Pin Assignment

8. Supported ATA Commands

8.1 Commands set

The following table defines some of the common ATA commands supported by the SSD X100. Specifics of each ATA command's operation can be found in the ATA/ATAPI Command Set ACS-2 document.

	Command Name	ATA8	Code
	Check Power Mode	M	E5h
	Data Set Management	O	06h
	Trim		01h
	Device Configuration Overlay	O	B1h
DCO sub-commands:	Restore		C0h
	Freeze Lock		C1h
	Identify		C2h
	Set		C3h
	Identify DMA		C4h
	Set DMA		C5h
	Download Microcode	O	92h
	Download (without offsets) and save microcode.		07h
	Execute Device Diagnostic	M	90h
	Flush Cache	M	E7h
	Flush Cache Ext	O	EAh
	Identify Device	M	Ech
	Idle	M	E3h
	Idle Immediate	M	E1h
	Initialize Drive Parameters	Obs	91h
	NOP	O	00h
	Read Buffer	O	E4h
	Read DMA	M	C8h
	Read DMA Ext	O	25h
	Read DMA w/o Retry	Obs	C9h
	Read FPDMA Queued	O	60h
	Read Log Ext	O	2Fh
	Read Multiple	M	C4h
	Read Multiple Ext	O	29h

Read Native Max Address	O	F8h
Read Native Max Addr Ext	O	27h
Read Sectors	M	20h
Read Sectors Ext	O	24h
Read Sectors w/o Retry	Obs	21h
Read Verify Sectors	M	40h
Read Verify Sectors Ext	O	42h
Read Verify Sectors w/o Retry	Obs	41h
Recalibrate	Obs	1Xh
Security Disable Password	O	F6h
Security Erase Prepare	O	F3h
Security Erase Unit	O	F4h
Security Freeze Lock	O	F5h
Security Set Password	O	F1h
Security Unlock	O	F2h
Seek	Obs	7Xh
Set Features	M	EFh
Set Features sub- commands:	Enable write cache	02h
	Set transfer mode	03h
	Enable Advanced Power Management (APM)	05h
	Enable SATA features	10h
	DMA Setup FIS Auto-Activate Optimization	02h
	Device-Initiated Interface Power Management	03h
	Software Setting Preservation	06h
	Disable read look-ahead	55h
	Disable reverting to power-on defaults	66h
	Disable write cache	82h
	Disable Advanced Power Management (APM)	85h
	Disable SATA features	90h
	DMA Setup FIS Auto-Activate Optimization	02h
	Device-Initiated Interface Power Management	03h
	Software Setting Preservation	06h
	Enable read look-ahead	AAh
	Enable reverting to power-on defaults	CCh
Set Max Address	O	F9h

Security Extension sub-commands:	Set Max Set Password		01h
	Set Max Lock		02h
	Set Max Unlock		03h
	Set Max Freeze Lock		04h
	Set Max Set Password DMA		05h
	Set Max Unlock DMA		06h
Set Max Address Ext	O	37h	
Set Multiple Mode	M	C6h	
Sleep	M	E6h	
Smart	O	B0h	
Smart sub-commands:	Read Attribute Values (Read Data)		D0h
	Read Attribute Thresholds	Obs	D1h
	Enable/Disable Attribute Autosave	O	D2h
	Save Attribute Values		D3h
	Execute Offline Immediate:		D4h
			00h
			01h
			02h
			7Fh
			81h
			82h
Read Log			D5h
Write Log			D6h
Enable Operations			D8h
Disable Operations			D9h
Read Status			DAh
Enable/Disable Automatic Offline	Obs	DBh	
Standby	M	E2h	
Standby Immediate	M	E0h	
Write Buffer	O	E8h	
Write DMA	M	CAh	
Write DMA Ext	O	35h	
Write DMA w/o Retry	Obs	CBh	
Write FPDMA Queued	O	61h	
Write Log Ext	O	3Fh	

Write Multiple	M	C5h
Write Multiple Ext	O	39h
Write Sectors	M	30h
Write Sectors Ext	O	34h
Write Sectors w/o Retry	Obs	31h
Write Uncorrectable Ext	O	45h
Pseudo-UECC with Logging		55h

M = Mandatory. O = Optional. Obs = Obsolete, But Supported

Table 8-1: Supported ATA Commands

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8.2 Identify Data

The following table defines the specifics of the Identify Data returned by the SSD X100.

Word Address	Default Value	Total Bytes	Data Field Type Information
0	0040h	2	ATA General configuration: bit-significant information
1	3FFFh	2	ATA Default number of cylinders (depends on capacity)
2	C837h	2	Reserved
3	0010h	2	Default number of heads
4-5	0000h	4	Obsolete
6	003Fh	2	Default number of sectors per track
7-9	0000h	6	Obsolete
10-19	ASCII	20	Serial number in ASCII (left-justified)
20-22	0000h	6	Obsolete
23-26	MJ.MN.XX	8	Firmware revision in ASCII (left-justified)
27-46	SanDisk SD5SX2XXXG	40	Model number in ASCII (left-justified) for SSD X00. SKU without dash; X depends on capacity and form factor.
47	8001h	2	Maximum No. of sectors in Read/Write Multiple command
48	4000h	2	Trusted Computing feature set is not supported
49	2F00h	2	LBA and MWDMA modes supported
50	4000h	2	Capabilities
51	0200h	2	PIO data transfer cycle timing mode
52	0000h	2	Obsolete
53	0007h	2	Field validity
54	3FFFh	2	Current number of cylinders
55	0010h	2	Current number of heads
56	003Fh	2	Current sectors per track
57-58	XXXXh	4	Current capacity in sectors (LBAs)
59	0101h	2	Multiple sector setting is valid (Multiple = 1)
60-61	XXXXh	4	Total number of sectors addressable in LBA Mode
62	0000h	2	Obsolete
63	0007h	2	Bits:15-8: Multiword DMA mode active Bits: 0-7: Multiword DMA modes supported
64	0003h	2	Advanced PIO modes supported
65	0078h	2	Minimum multiword DMA transfer cycle time per word (ns)

Word Address	Default Value	Total Bytes	Data Field Type Information
66	0078h	2	Recommended multiword DMA transfer cycle time per word in ns
67	0078h	2	Minimum PIO transfer without flow control
68	0078h	2	Minimum PIO transfer with IORDY flow control
69	4020h	2	ATA8-ACS2 Additional Supported
70-74	0000h	10	Reserved
75	001Fh	2	Queue Depth
76	870Eh	2	SATA capabilities
77	0006h	2	SATA Additional capabilities (0002=1.5Gb/s, 0004=3Gb/s, 0006=6Gb/s)
78	004Ch	2	SATA Features Supported
79	0040h	2	SATA Features Enabled
80	01F0h	2	Major Version number
81	0028h	2	Minor Version number
82	346Bh	2	Command set supported
83	7D09h	2	Command sets supported
84	4123h	2	Command set/feature supported extension
85	3469h	2	Command set/feature enabled
86	BC09h	2	Command set/feature enabled
87	4123h	2	Command set/feature default
88	207Fh	2	Ultra DMA Mode supported and selected
89	0001h	2	Time required for security erase-unit completion (all capacities complete < 2 minutes)
90	0001h	2	Time required for Enhanced security erase completion
91	0080h	2	Current advanced power management value
92	FFFEh	2	Master Password Identifier
93	0000h	2	Hardware Reset Result
94	0000h	2	Current AAM Value
95	0000h	2	Stream Min Request Size
96	0000h	2	Streaming Transfer Time-DMA
97	0000h	2	Streaming Access Latency
98-99	0000h	4	Streaming Performance Granularity
100-103	XXXXh	8	48-bit # of LBA's

Word Address	Default Value	Total Bytes	Data Field Type Information
104	0000h	2	Streaming Transfer Time-PIO
105	0010h	2	Max # 512-byte Blocks in LBA Range Entries
106	4000h	2	Physical Sector Size/Logical
107	0000h	2	Inter-Seek Delay for ISO7779
108-111	5001B44XXXXXXXXXh	8	WWN
112-115	0000h	8	Reserved
116	0000h	2	Reserved for TLC
117-118	0000h	4	Logical Sector Size
119	400Ch	2	Command/Feature Sets Supported
120	400Ch	2	Command/Feature Sets Enabled
121-126	0000h	12	Reserved
127	0000h	2	Obsolete
128	0021h	2	Security Status
129-159	0000h	62	Reserved vendor-unique bytes
160-167	0000h	16	Reserved
168	0003h/0005h	2	Device Nominal Form Factor 2.5"/module
169	0001h	2	ATA8-ACS2 Data Set Management Support
170-175	0000h	12	Reserved
176-205	2020h	60	Current Media Serial Number (not supported)
206	0000h	2	SCT Command Transport
207-208	0000h	4	Reserved for CE-ATA
209	4000h	2	Alignment-Logical within Physical Block
210-211	0000h	4	Wr/Rd/Vfy Sector Count Mode 3
212-213	0000h	4	Wr/Rd/Vfy Sector Count Mode 2
214	0000h	2	NV Cache Capabilities
215-216	0000h	4	NV Cache Size in Logical Blocks
217	0001h	2	Nominal Media Rotation Rate
218	0000h	2	Reserved
219	0000h	2	NV Cache Options

Word Address	Default Value	Total Bytes	Data Field Type Information
220	0000h	2	Wr/Rd/Vfy Feature Set-Current Mode
221	0000h	2	Reserved
222	103Fh	2	Transport Major Version Number
223	0000h	2	Transport Minor Version Number
224-233	0000h	20	Reserved for CE-ATA
234	0000h	2	Min Sector Count for Download Microcode Mode 3
235	0000h	2	Max Sector Count for Download Microcode Mode 3
236-254	0000h	38	Reserved for CE-ATA
255	XXXXh	2	Integrity Word-Checksum

Table 8-2: Identify Data Values

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8.3 Log Pages

The following table defines the list of supported Log Pages accessible through SMART Write Log, SMART Read Log, Read Log Ext and Write Log Ext commands.

Log Address	Total Pages	Log Address Description	Access
00h	1	General Purpose Log Directory	GPL, SMART Log
01h	1	Summary SMART Error Log	SMART Log
02h	2	Comprehensive SMART Error log	SMART Log
03h	1	Extended Comprehensive SMART Error Log	GPL
06h	1	SMART Self-Test Log	SMART Log
07h	1	Extended SMART Self-Test log	GPL
10h	1	NCQ Error Log	GPL
11h	1	SATA PHY Event Counters Log	GPL
80-9Fh	16	Host Vendor-specific Logs	GPL, SMART Log

Table 8-3: Supported SMART Log Pages

9. Ordering information

SD5SXP-CCCU-YYYYT	
SD	SanDisk
5	Generation: 5
S	SATA
X	Form factor: B – 2.5" 7.0mm cased form factor C – 2.5" 9.5mm cased form factor F – mSATA form factor
P	2 – MLC
CCC	Capacity: 032 064 128 256 512
U	Units: G – GB
YYYY	Customer code reference
T	NAND Technology: E - 24nm MLC ABL

Table 9-1: SSD X100 Ordering Information

Refer to the examples below as reference for ordering SKUs.

SKU #	Details
SD5SB2-256G	SSD X100 256GB in 7.0mm cased form factor
SD5SF2-032G	SSD X100 32GB in mSATA form factor

Table 9-2: Examples of decoded SKU for SSD X100 Products

10. Contact information

USA

Tel: +1-408-470-4440
Fax: +1-408-470-4470
OEMinfo@sandisk.com

China

Tel: +86-755-8348-5218
Fax: +86-755-8348-5418
OEMChina@sandisk.com

Taiwan

Tel: +886-2-2515-2522
Fax: +886-2-2515-2295
OEMAsia@sandisk.com

Korea

Tel: +82-2-3452-9079
Fax: +82-2-3452-9145

Japan

Tel: +81-3-5423-8101
Fax: +81-3-5423-8102
OEMJapan@sandisk.com

Europe

Tel: +33-(1)-43-37-2131
Fax: +33-(1)-43-37-2111
OEMEurope@sandisk.com

Rest of the World & Israel

Tel: +972-9-764-5000
Fax: +972-3-548-8666

For more information, please visit www.sandisk.com/SSD